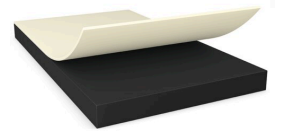




tesa® LTR 58489

제품 정보



tesa® Low Temperature Reactive (LTR)

제품 설명

tesa® Low Temperature Reactive (LTR) 58489 제품은 적당한 온도에서 활성화되는 반응성 장착 테이프입니다. 이 블랙 양면 테이프는 무기재료, PE 코팅된 종이 라이너로 보호됩니다.

조립 과정에서 가해지는 적당한 열과 압력에 의해 활성화된다.

특성

- Extremely high bonding performance and reliability, even on slim bonding areas and thin design gaps
- Excellent shock resistance
- Activated at low temperature and pressure
- Sebum resistant
- Very low oozing ratio
- At room temperature tesa® LTR 58489 is not tacky.
- tesa® LTR 58489 is free of halogen and compliant with current RoHS directive.

Applications

tesa® LTR 58489 특히 온도에 민감한 기판의 구조적 접합에 권장됩니다:

- Bonding of fabrics
- Bonding of plastics
- Mounting of sensitive electronic parts

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

제품 구조

- | | | | |
|----------|---------------|-------|--------|
| • 기재 소재 | 없음 | • 총두께 | 300 µm |
| • 점착제 종류 | 저온 활성화 반응 점착제 | • 컬러 | 검정 |
| • 이형지 종류 | PE 코팅된 직물 | | |

속성 / 성능 값

- | | | | |
|----------|-----------|---------------|-----------|
| • 낮은 VOC | very good | • 점착력 (푸쉬 아웃) | 7.5 N/mm² |
|----------|-----------|---------------|-----------|

비고

Technical recommendations:

최신정보는 왼쪽 링크를 클릭하세요. <http://l.tesa.com/?ip=58489>



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tesa® LTR 58489 is not self adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

1. Pre-lamination:

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

- Temperature¹ 50 – 60 °C
- Pressure² 1 – 3 bar
- Time 5 – 20 s

Short-time exposure to 60°C bond line temperature during pre-lamination does not impact final bonding potential.

2. Bonding:

Remove the liner from tape after the pre-lamination step.

Position the second component. Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

Setting:

- Temperature¹ 75 – 110 °C
- Pressure² 2 – 4 bar
- Time 10 – 480 s

Temperature, pressure and time will depend upon the type and thickness of the substrates. Generally, thicker substrates or lower bonding temperatures will require longer bonding times. Short cycle times can be achieved at 110 °C bond line temperature. For activation at lower temperatures, increase the heat-press time or combine a short heat-press step with oven curing. To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours.

Bonding strength values were obtained under standard laboratory conditions (Material: PC/PC; bonding conditions: temperature (jig) = 90 °C; pressure = 5 bar; time = 120 sec).

Storage:

tesa recommends storage in original packaging in cool and dry conditions. Low Temperature Reactive should not be exposed to more than 35°C before bonding (during transport, storage and converting).

The minimum guaranteed shelf life is 15 months after coating. For the actual shelf life please refer to the best before date on the label in the log roll core.

¹ 'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

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² 'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.

면책사항

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